504205424 01/31/2017

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1 EPAS ID: PAT4252101 Stylesheet Version v1.2

SUBMISSION TYPE: NEW ASSIGNMENT NATURE OF CONVEYANCE: ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
KEN TACHIBANA	12/19/2016
TAKAHIRO HATTORI	12/21/2016

RECEIVING PARTY DATA

Name:	SENJU METAL INDUSTRY CO., LTD.	
Street Address:	23, SENJU-HASHIDO-CHO, ADACHI-KU	
City:	TOKYO	
State/Country:	JAPAN	
Postal Code:	120-8555	

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	15500740

CORRESPONDENCE DATA

Fax Number: (412)471-4094

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent

using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

412-471-8815 Phone:

Email: assignments@webblaw.com Correspondent Name: THE WEBB LAW FIRM, P.C. Address Line 1: ONE GATEWAY CENTER

Address Line 2: 420 FT. DUQUESNE BLVD, SUITE 1200 Address Line 4: PITTSBURGH, PENNSYLVANIA 15222

ATTORNEY DOCKET NUMBER: 7466-1606251 NAME OF SUBMITTER: BRYAN P. CLARK SIGNATURE: /Bryan P. Clark/ **DATE SIGNED:** 01/31/2017

Total Attachments: 3

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> **PATENT** REEL: 041134 FRAME: 0981 504205424

RECORDATION FORM COVER SHEET		
	S ONLY	
	se record the attached documents or the new address(es) below.	
1. Name of conveying party(ies) Ken TACHIBANA	2. Name and address of receiving party(ies)	
Takahiro HATTORI	Name: Senju Metal Industry Co., Ltd.	
	Internal Address:	
Additional name(s) of conveying party(ies) attached? Yes No. Nature of conveyance/Execution Date(s): Execution Date(s) 12/19/2016 and 12/21/2016	Street Address: 23, Senju-Hashido-cho, Adachi-ku	
✓ Assignment		
Security Agreement Change of Name	City: Tokyo	
Joint Research Agreement	State:	
Government Interest Assignment Executive Order 9424, Confirmatory License	Country: JAPAN Zip: 120-8555	
Other	Additional name(s) & address(es) attached? Yes V No	
A. Patent Application No.(s) 15/500,740 Additional numbers at	B. Patent No.(s) tached?	
5. Name and address to whom correspondence concerning document should be mailed:	6. Total number of applications and patents involved: 1	
Name: Russell D. Orkin		
Internal Address: The Webb Law Firm	7. Total fee (37 CFR 1.21(h) & 3.41) \$ <u>0</u>	
	Authorized to be charged to deposit account	
Street Address: One Gateway Center	Enclosed	
420 Ft. Duquesne Blvd., Ste 1200	None required (government interest not affecting title)	
City: Pittsburgh	8. Payment Information	
State: PA Zip: 15222		
Phone Number: 412-471-8815	5 (10.00)	
Docket Number: 7466 - 1606251	Deposit Account Number	
Email Address: assignments@webblaw.com	Authorized User Name	
9. Signature: /Bryan P. Clark/	January 31, 2017	
Signature	Date	
Bryan P. Clark Name of Person Signing	Total number of pages including cover sheet, attachments, and documents: 3	
	et) should be faxed to (571) 273-0140, or mailed to: of the USPTO, P.O.Box 1450, Alexandria, V.A. 22313-1450	

PATENT
REEL: 041134 FRAME: 0982

INTERNATIONAL Application No.
Attorney Docket No
<u>ASSIGNMENT</u>
WHEREAS, as a below named inventor, I have invented certain new and useful improvements in
Solder Alloy, SolderBall, Chip Solder, Solder Paste and Solder Joint (Invention Title)
for which I have this day executed an application for a United States Patent (hereinafter "said application"). AND/OR
for which an application for a United States Patent was filed on (mm/dd/yyyy) and bears Application Number (hereinafter "said application"). AND/OR
for which an international patent application was filed under the Patent Cooperation Treaty on <u>02/15/2016</u> (mm/dd/yyyy), bearing Application No. <u>PCT/JP2016/054345</u> (hereinafter "said application").
AND, WHEREAS, Senju Metal Industry Co., Ltd., a corporation of Japan, having a place of business at 23, Senju-Hashido-cho, Adachi-ku, Tokyo 120-8555, Japan, hereinafter called the "assignee", is desirous of acquiring the entire right, title, and interest in and to said application and the inventions and improvements therein disclosed.
NOW, THEREFORE, for good and valuable consideration paid to me by said assignee, the receipt of which is hereby acknowledged, I as the inventor or as one of the inventors, hereinafter the assignor(s), do hereby assign, sell and transfer unto said assignee the full and exclusive right, title and interest in and to said application and the inventions and improvements therein disclosed for the United States and all foreign countries and any Letters Patent which may issue therefor in the United States and all foreign countries and all divisions, reissues, continuations, continuations-in-part, renewals and/or extensions thereof. Such assignment extends to the full ends of the terms of these applications and patents as fully and entirely as the same would have been held and enjoyed by me had this Assignment not been made.
I hereby authorize and request any attorney associated with The Webb Law Firm, Customer No. 28289, to insert here in parentheses (Application No. 15/500,740 , filed 02/15/2016) the filing date and application number of said application when known.

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improvements, that the same are unencumbered, that no license has been granted to make, use or vend the said inventions or improvements or any of them, and that I have the full right to make

I covenant that I am the lawful owner(s) of said application, inventions and

PATENT REEL: 041134 FRAME: 0983

this Assignment.

	INTERNATIONAL
Application	No
Attorney Docket No	. 7466-1606251

And for the consideration aforesaid, I agree individually and, if applicable, jointly that I will communicate to said assignee or the representatives thereof any facts known to me respecting said inventions and improvements, and will, upon request but without expense to me, testify in any legal proceedings, sign all lawful papers, execute all divisional, reissue, continuation, continuation-in-part, renewal and/or extension applications, make all rightful oaths, and generally do all other and further lawful acts deemed necessary or expedient by said assignee or by counsel for said assignee to assist or enable said assignee to obtain and enforce full benefits from the rights and interests herein assigned. This Assignment shall be binding upon my heirs, executors, administrators and/or assigns, and shall inure to the benefit of the heirs, executors, administrators, successors and/or assigns, as the case may be, of said assignee.

1. FULL NAME OF ASSIGNOR: Ken TACHIBANA	RESIDENCE:
Ken IACHIDANA	Chiba, Japan
EXECUTED this 14 day of 10 combey,	
	Ken Tadibana
	Signature
WITNESS:	
Gukiko Hashimo	
2. FULL NAME OF ASSIGNOR: Takahiro HATTORI	RESIDENCE: Tochigi, Japan
EXECUTED this 21 day of Dec.	
	Takahiro HATTORI
	SIGNATURE
WITNESS:	
Yuhike Hashimo	
Checked Box indicatesadditional page	(s) for inventor signatures.

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RECORDED: 01/31/2017